

**CLASS 2 BOARD      PROPOSED ON: 05/28/2010**

Proposed									
	Conventional	Micro-laser drill with B-Stage	Visual only	micro-laser DDI WILL BE TAKING MY 1-3 AND STACK IT WITH THE 1-2 & 2-3 VIA'S	Visual only	Micro-laser DDI WILL BE TAKING MY 1-6 AND STACK IT WITH THE 1-2 & 2-6 VIA'S AND MY 7-12 AND STACKING IT WITH 11-12 & 7-11 VIA	conventional		
1 copper 0.0005	1 thru 20	.004 hole 1-2 u		.008 hole 1-3 u				SURFACE	
dielectric 0.0025		.010 pad	.008 hole 2-3 u	.016 pad					
2 copper 0.0005					.008 hole 2 thru 10		.008 hole 1 thru 10		GND /PWR PLANE
dielectric 0.004									Pair Layer (3.5trace---5.5 space)
3 copper 0.0007					.016 pad		.016 pad		GND /PWR PLANE
dielectric 0.005									Pair Layer (3.5trace---5.5 space)
4 copper 0.0014									GND /PWR PLANE
dielectric 0.004									Pair Layer (3.5trace---5.5 space)
5 copper 0.0007									GND /PWR PLANE
dielectric 0.005									Pair Layer (3.5trace---5.5 space)
6 copper 0.0005									GND /PWR PLANE
dielectric 0.005									Pair Layer (3.5trace---5.5 space)
7 copper 0.0005									GND /PWR PLANE
dielectric 0.006									Pair Layer (3.5trace---5.5 space)
8 copper 0.0005									GND /PWR PLANE
dielectric 0.005									Pair Layer (3.5trace---5.5 space)
9 copper 0.0005									GND /PWR PLANE
dielectric 0.006									Pair Layer (3.5trace---5.5 space)
10 copper 0.0005									GND /PWR PLANE
dielectric 0.006									GND /PWR PLANE
11 copper 0.0005						Pair Layer (3.5trace---5.5 space)			
dielectric 0.006						GND /PWR PLANE			
12 copper 0.0007						Pair Layer (3.5trace---5.5 space)			
dielectric 0.006						GND /PWR PLANE			
13 copper 0.0007						Pair Layer (3.5trace---5.5 space)			
dielectric 0.005						GND /PWR PLANE			
14 copper 0.0007						Pair Layer (3.5trace---5.5 space)			
dielectric 0.005						GND /PWR PLANE			
15 copper 0.0007						Pair Layer (3.5trace---5.5 space)			
dielectric 0.004						GND /PWR PLANE			
16 copper 0.0007						Pair Layer (3.5trace---5.5 space)			
dielectric 0.004						GND /PWR PLANE			
17 copper 0.0007					.008 hole 11 thru 19	.008 hole 9 thru 20	Pair Layer (3.5trace---5.5 space)		
dielectric 0.005					.016 pad	.016 pad	GND /PWR PLANE		
18 copper 0.0007			.008 hole 18-19 u	.008 hole 18-20 u					
dielectric 0.004			.016 pad	.016 pad					
19 copper 0.0005		.004 hole 19-120u		.016 pad					
dielectric 0.0025									
20 copper 0.0005		.010 pad							
								SURFACE/GND	

thk	0.004 ***plus plating (.001)x4 places on lyrs 2, 6, 7, 11
	0.1067

D

C

B

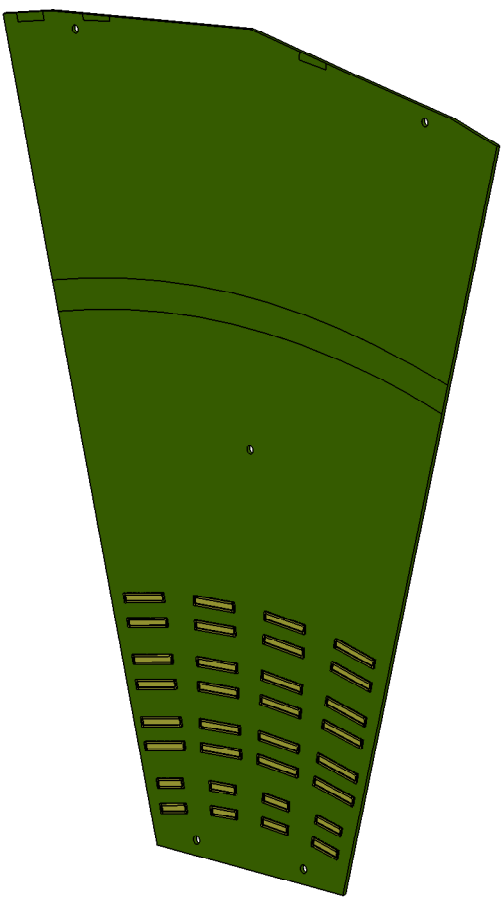
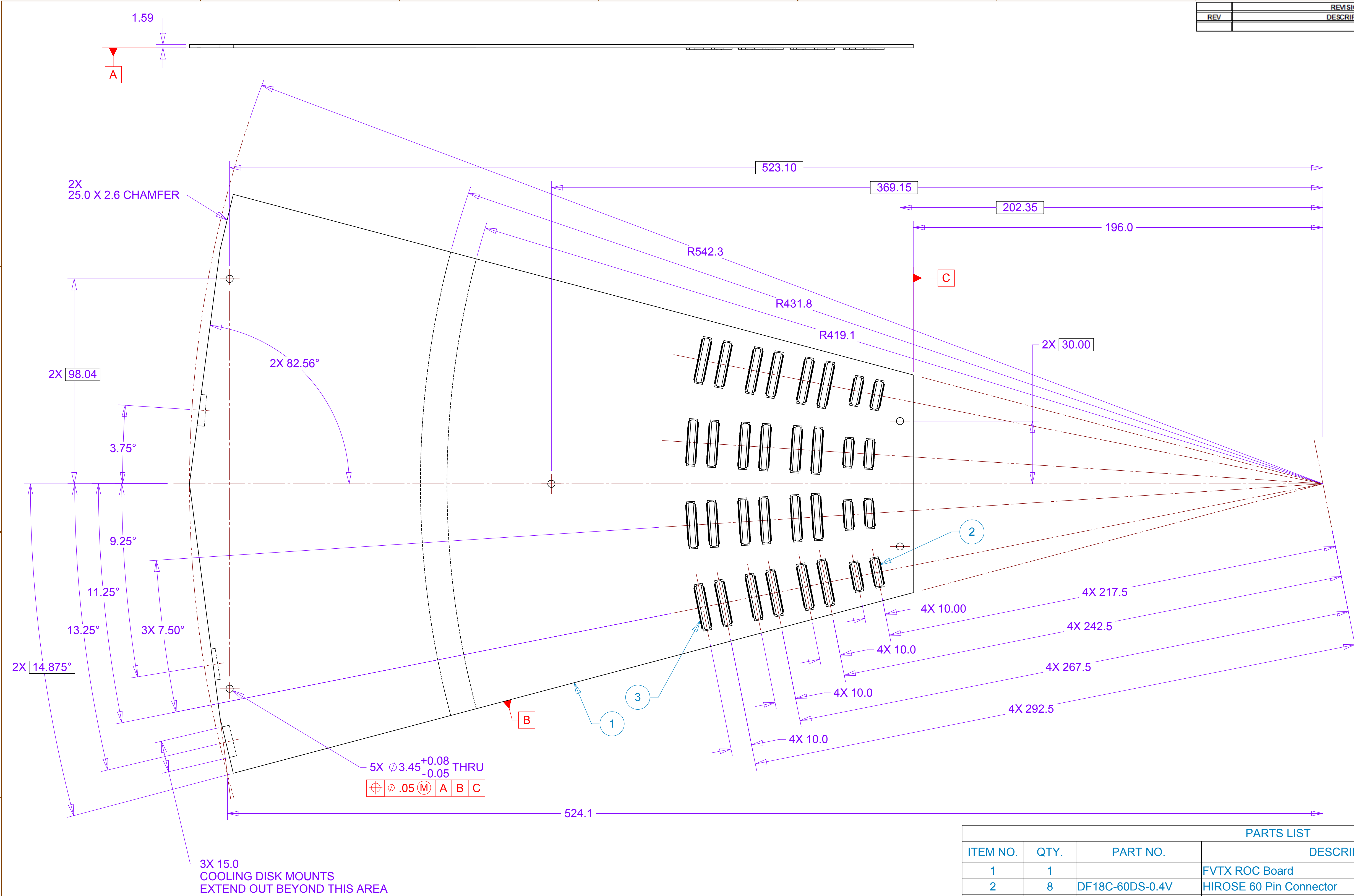
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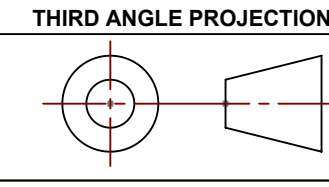
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A



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PARTS LIST				
ITEM NO.	QTY.	PART NO.	DESCRIPTION	MATERIAL
1	1		FVTX ROC Board	
2	8	DF18C-60DS-0.4V	HIROSE 60 Pin Connector	
3	24	DF18C-100DS-0.4V	HIROSE 100 Pin Connector	

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS -TOLERANCES-		CAD GENERATED DRAWING, DO NOT MANUALLY UPDATE DO NOT SCALE DRAWING		<div><i><b>HYTEC, INC</b></i></div> <div>TITLE</div> <div><b>PHENIX CENTRAL UPGRADE FVTX READOUT CARD OUTLINE</b></div>		
DECIMALS .X = +/- .1 .XX = +/- .01 .XXX = +/- .001						
ANGULAR = +/- .30"						
SURFACE FINISH = 250						
FINISH						
PART NO. <b>111-PHX-02-4001-1</b>			<u>SIGNATURE</u>	<u>DATE</u>	DWG. NO. <b>111-PHX-02-4001 D</b>	SHEET NO. <b>1 of 1</b>
		<u>Designer</u>	Roger L. Smith	9/30/2009		
		<u>Drawn</u>	Roger L. Smith	9/30/2009		
		<u>Checked</u>				
		<u>Engineer</u>	RJ Ponchione	9/30/2009		
		<u>Approved</u>			SCALE 1:1	REVISION -